



Dual INT-A-PAK Low Profile "Half Bridge" (Trench PT IGBT), 400 A

Proprietary Vishay IGBT Silicon "L Series"



Dual INT-A-PAK Low Profile

FEATURES

- Trench PT IGBT technology
Low VCE(on)
Square RBSOA
HEXFRED antiparallel diode with ultrasoft reverse recovery characteristics
Industry standard package
Al2O3 DBC
UL approved file E78996
Designed for industrial level
Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS COMPLIANT

Table with 2 columns: Parameter and Value. Includes VCES (600 V), IC DC at TC = 103 °C (400 A), VCE(on) (typical) at 400 A, 25 °C (1.30 V), Speed (DC to 1 kHz), Package (Dual INT-A-PAK low profile), and Circuit configuration (Half bridge).

BENEFITS

- Increased operating efficiency
Performance optimized as output inverter stage for TIG welding machines
Direct mounting on heatsink
Very low junction to case thermal resistance

Table with 5 columns: PARAMETER, SYMBOL, TEST CONDITIONS, MAX., UNITS. Lists absolute maximum ratings for VCES, IC, ICM, ILM, IF, VGE, PD, VISOL, and temperature range.

Note

(1) Maximum continuous collector current must be limited to 500 A to do not exceed the maximum temperature of terminals



<b>ELECTRICAL SPECIFICATIONS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{BR(CEs)}$	$V_{GE} = 0\text{ V}, I_C = 500\text{ }\mu\text{A}$	600	-	-	V
Collector to emitter voltage	$V_{CE(on)}$	$V_{GE} = 15\text{ V}, I_C = 200\text{ A}$	-	1.13	1.24	
		$V_{GE} = 15\text{ V}, I_C = 400\text{ A}$	-	1.30	1.52	
		$V_{GE} = 15\text{ V}, I_C = 200\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.03	-	
		$V_{GE} = 15\text{ V}, I_C = 400\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.26	-	
Gate threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 9.6\text{ mA}$	4.9	5.9	8.8	
		$V_{CE} = V_{GE}, I_C = 9.6\text{ mA}, T_J = 125\text{ }^\circ\text{C}$	-	3.2	-	
Temperature coefficient of threshold voltage	$\Delta V_{GE(th)}/\Delta T$	$V_{CE} = V_{GE}, I_C = 9.6\text{ mA}, (25\text{ }^\circ\text{C to } 125\text{ }^\circ\text{C})$	-	-27	-	mV/°C
Forward transconductance	$g_{fe}$	$V_{CE} = 20\text{ V}, I_C = 50\text{ A}$	-	74	-	S
Transfer characteristics	$V_{GE}$	$V_{CE} = 20\text{ V}, I_C = 400\text{ A}$	-	10.7	-	V
Collector to emitter leakage current	$I_{CES}$	$V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}$	-	5	200	$\mu\text{A}$
		$V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	1.5	-	mA
Diode forward voltage drop	$V_{FM}$	$I_{FM} = 200\text{ A}$	-	1.42	1.55	V
		$I_{FM} = 400\text{ A}$	-	1.76	1.98	
		$I_{FM} = 200\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.43	-	
		$I_{FM} = 400\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.88	-	
Gate to emitter leakage current	$I_{GES}$	$V_{GE} = \pm 20\text{ V}$	-	-	$\pm 750$	nA

<b>SWITCHING CHARACTERISTICS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on switching energy	$E_{on}$	$I_C = 400\text{ A}, V_{CC} = 300\text{ V}, V_{GE} = 15\text{ V}, R_g = 1.5\text{ }\Omega, L = 500\text{ }\mu\text{H}, T_J = 25\text{ }^\circ\text{C}$	-	6.3	-	mJ
Turn-off switching energy	$E_{off}$		-	45	-	
Total switching energy	$E_{tot}$		-	51.3	-	
Turn-on delay time	$t_{d(on)}$	$I_C = 400\text{ A}, V_{CC} = 300\text{ V}, V_{GE} = 15\text{ V}, R_g = 1.5\text{ }\Omega, L = 500\text{ }\mu\text{H}, T_J = 25\text{ }^\circ\text{C}$	-	633	-	ns
Rise time	$t_r$		-	254	-	
Turn-off delay time	$t_{d(off)}$		-	715	-	
Fall time	$t_f$		-	490	-	
Turn-on switching loss	$E_{on}$		-	7.2	-	
Turn-off switching loss	$E_{off}$	-	74	-		
Total switching loss	$E_{tot}$	-	81.2	-		
Turn-on delay time	$t_{d(on)}$	$I_C = 400\text{ A}, V_{CC} = 300\text{ V}, V_{GE} = 15\text{ V}, R_g = 1.5\text{ }\Omega, L = 500\text{ }\mu\text{H}, T_J = 125\text{ }^\circ\text{C}$	-	595	-	ns
Rise time	$t_r$		-	250	-	
Turn-off delay time	$t_{d(off)}$		-	950	-	
Fall time	$t_f$		-	865	-	
Reverse bias safe operating area	RBSOA	$T_J = 150\text{ }^\circ\text{C}, I_C = \text{n/a}, V_{CC} = 300\text{ V}, V_P = 600\text{ V}, R_g = 1.5\text{ }\Omega, V_{GE} = 15\text{ V to } 0\text{ V}, L = 500\text{ }\mu\text{H}$	Fullsquare			
Diode reverse recovery time	$t_{rr}$	$I_F = 400\text{ A}, R_g = 1.5\text{ }\Omega, V_{CC} = 300\text{ V}, T_J = 25\text{ }^\circ\text{C}$	-	123	-	ns
Diode peak reverse current	$I_{rr}$		-	107	-	A
Diode recovery charge	$Q_{rr}$		-	8.1	-	$\mu\text{C}$
Diode reverse recovery time	$t_{rr}$	$I_F = 400\text{ A}, R_g = 1.5\text{ }\Omega, V_{CC} = 300\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	167	-	ns
Diode peak reverse current	$I_{rr}$		-	140	-	A
Diode recovery charge	$Q_{rr}$		-	14.7	-	$\mu\text{C}$



THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS
Operating junction and storage temperature range	$T_J, T_{Stg}$	-40	-	150	$^{\circ}\text{C}$
Junction to case per leg	IGBT	-	-	0.08	$^{\circ}\text{C}/\text{W}$
	Diode	-	-	0.4	
Case to sink per module	$R_{thCS}$	-	0.05	-	
Mounting torque	case to heatsink: M6 screw	4	-	6	Nm
	case to terminal 1, 2, 3: M5 screw	2	-	5	
Weight		-	270	-	g

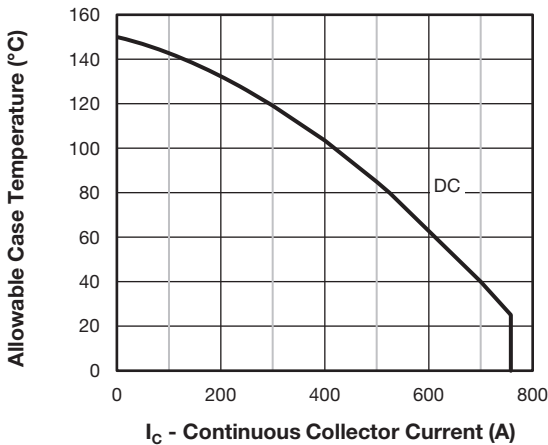


Fig. 1 - Maximum IGBT Continuous Collector Current vs. Case Temperature

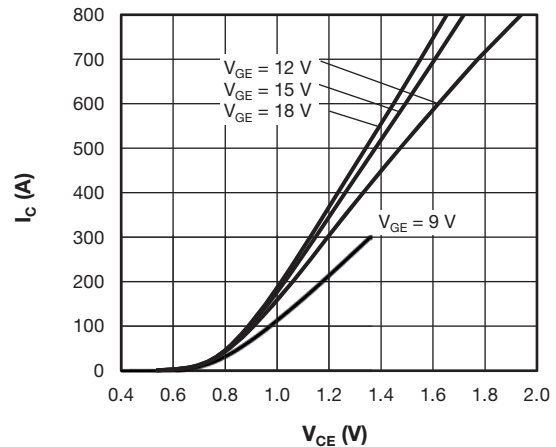


Fig. 3 - Typical IGBT Output Characteristics,  $T_J = 125^{\circ}\text{C}$

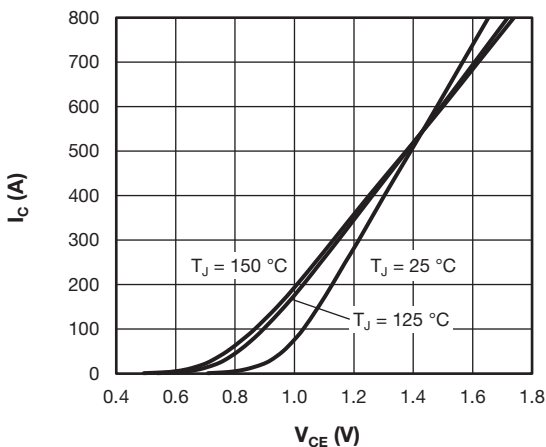


Fig. 2 - Typical IGBT Output Characteristics,  $V_{GE} = 15\text{ V}$

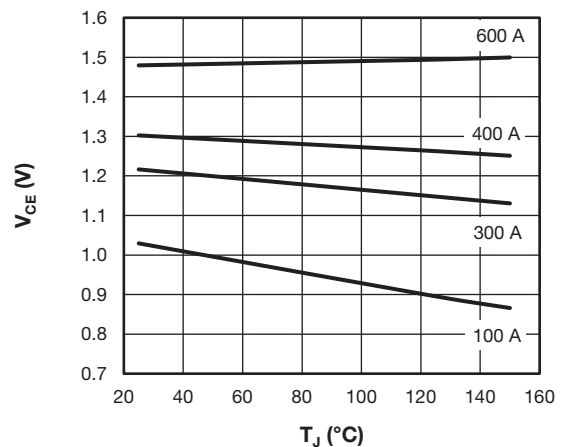


Fig. 4 - Collector to Emitter Voltage vs. Junction Temperature

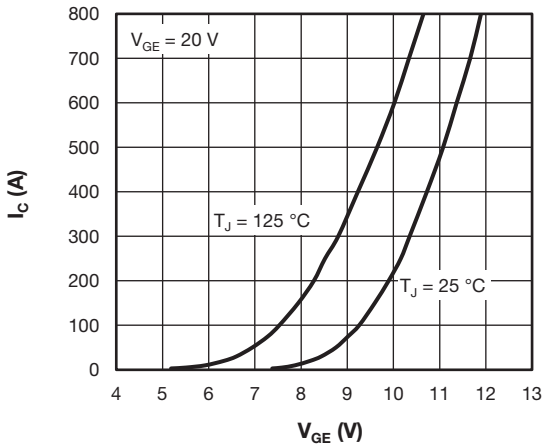


Fig. 5 - Typical IGBT Transfer Characteristics

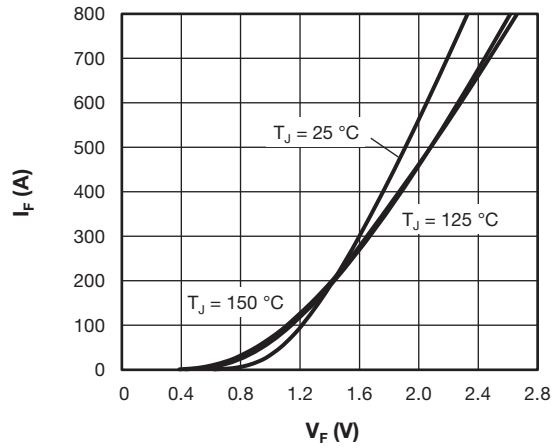


Fig. 8 - Typical Diode Forward Characteristics

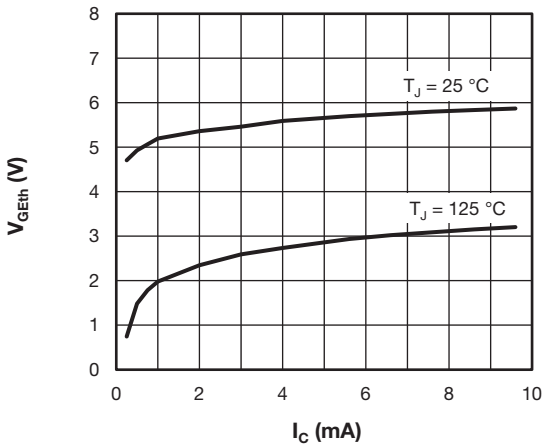


Fig. 6 - Typical IGBT Gate Threshold Voltage

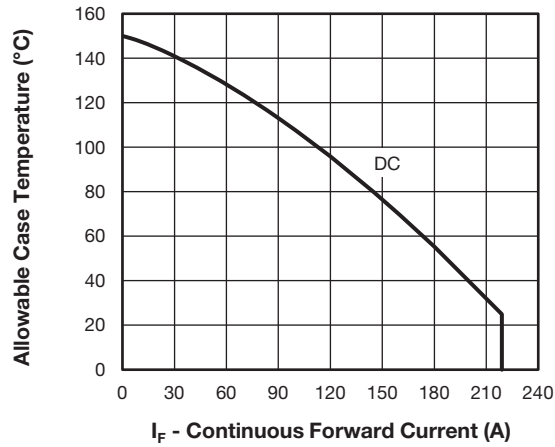


Fig. 9 - Maximum Diode Continuous Forward Current vs. Case Temperature

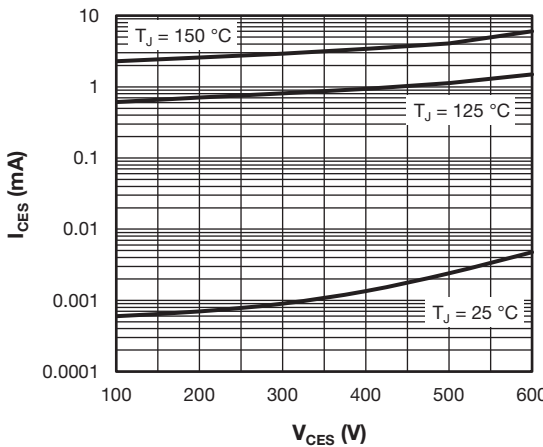


Fig. 7 - Typical IGBT Zero Gate Voltage Collector Current

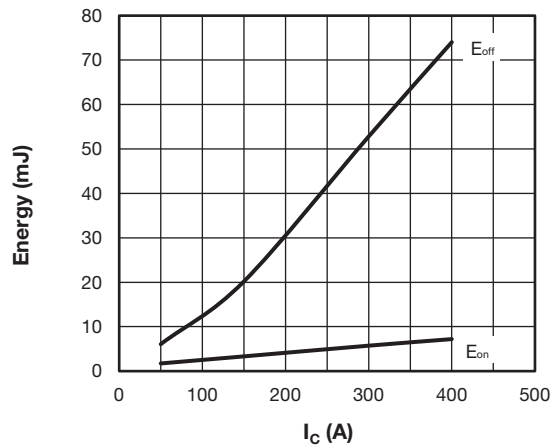


Fig. 10 - Typical IGBT Energy Loss vs. Ic  
T<sub>J</sub> = 125 °C, V<sub>CC</sub> = 300 V, R<sub>g</sub> = 1.5 Ω, V<sub>GE</sub> = 15 V, L = 500 μH

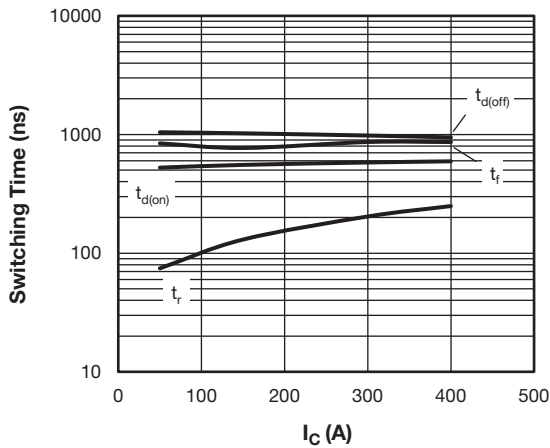


Fig. 11 - Typical IGBT Switching Time vs.  $I_C$   
 $T_J = 125^\circ\text{C}$ ,  $V_{CC} = 300\text{ V}$ ,  $R_g = 1.5\ \Omega$ ,  $V_{GE} = 15\text{ V}$ ,  $L = 500\ \mu\text{H}$

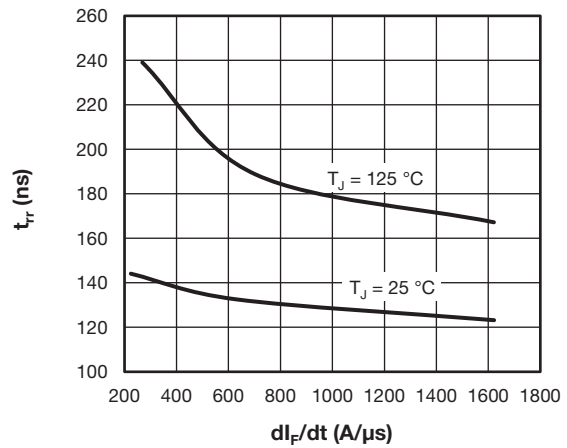


Fig. 14 - Typical Diode Reverse Recovery Time vs.  $di_F/dt$   
 $V_{CC} = 300\text{ V}$ ,  $I_F = 400\text{ A}$

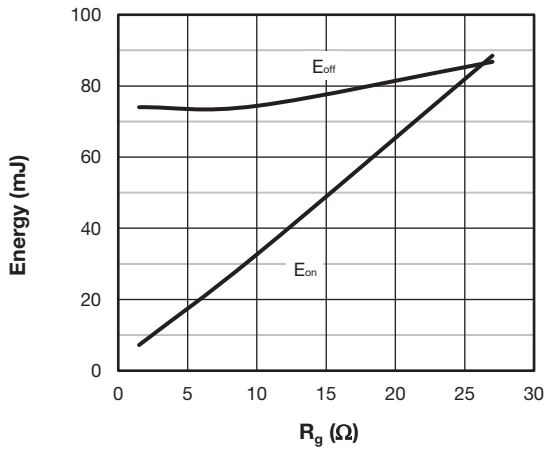


Fig. 12 - Typical IGBT Energy Loss vs.  $R_g$   
 $T_J = 125^\circ\text{C}$ ,  $V_{CC} = 300\text{ V}$ ,  $I_C = 400\text{ A}$ ,  $V_{GE} = 15\text{ V}$ ,  $L = 500\ \mu\text{H}$

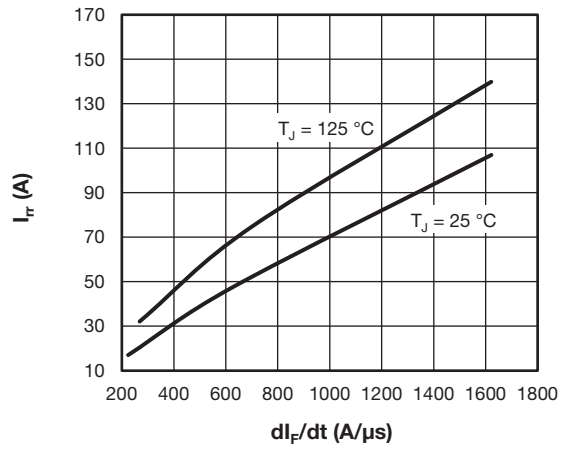


Fig. 15 - Typical Diode Reverse Recovery Current vs.  $di_F/dt$   
 $V_{CC} = 300\text{ V}$ ,  $I_F = 400\text{ A}$

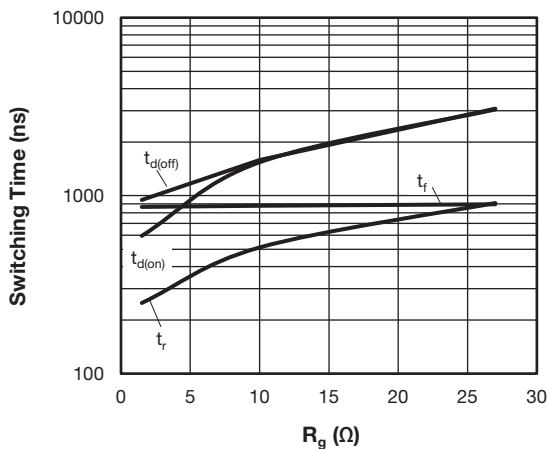


Fig. 13 - Typical IGBT Switching Time vs.  $R_g$   
 $T_J = 125^\circ\text{C}$ ,  $V_{CC} = 300\text{ V}$ ,  $I_C = 400\text{ A}$ ,  $V_{GE} = 15\text{ V}$ ,  $L = 500\ \mu\text{H}$

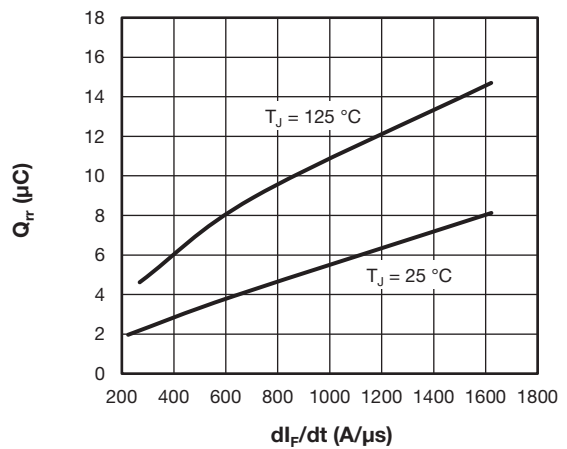


Fig. 16 - Typical Diode Reverse Recovery Charge vs.  $di_F/dt$   
 $V_{CC} = 300\text{ V}$ ,  $I_F = 400\text{ A}$

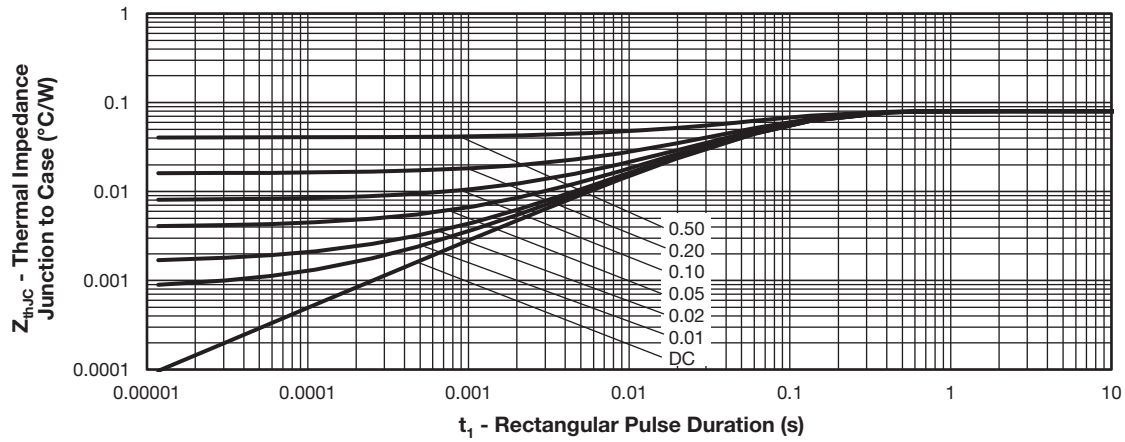


Fig. 17 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics - (IGBT)

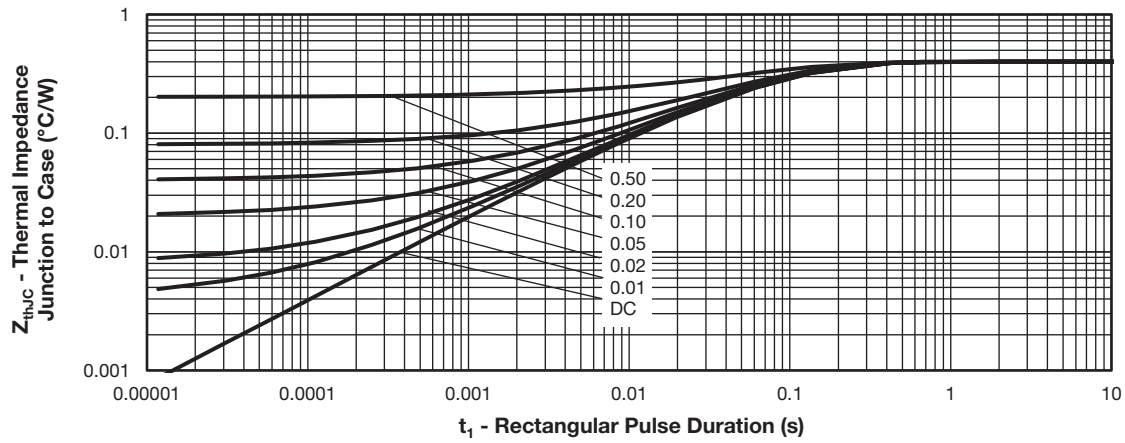


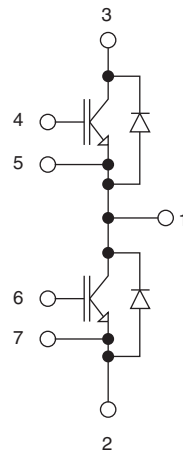
Fig. 18 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics - (Diode)

## ORDERING INFORMATION TABLE

Device code	<b>VS-</b>	<b>G</b>	<b>P</b>	<b>400</b>	<b>T</b>	<b>D</b>	<b>60</b>	<b>S</b>
	①	②	③	④	⑤	⑥	⑦	⑧

- 1 - Vishay Semiconductors product
- 2 - Insulated gate bipolar transistor (IGBT)
- 3 - P = trench PT IGBT technology
- 4 - Current rating (400 = 400 A)
- 5 - Circuit configuration (T = half bridge)
- 6 - Package indicator (D = dual INT-A-PAK low profile)
- 7 - Voltage rating (60 = 600 V)
- 8 - Speed / type (S = standard speed IGBT)

## CIRCUIT CONFIGURATION



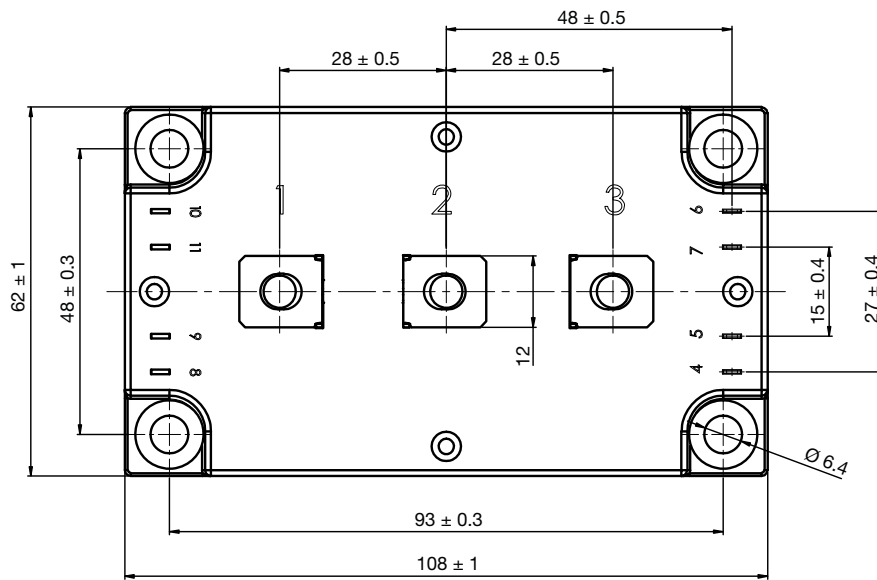
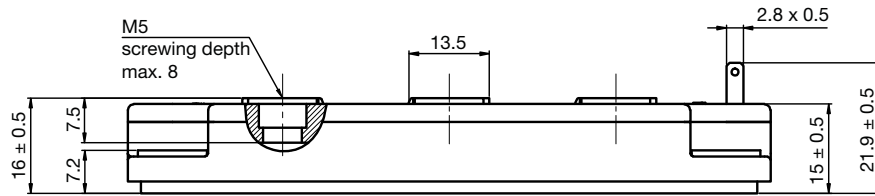
### LINKS TO RELATED DOCUMENTS

Dimensions	<a href="http://www.vishay.com/doc?95435">www.vishay.com/doc?95435</a>
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## Dual INT-A-PAK Low Profile

**DIMENSIONS** in millimeters







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